

High Efficiency Standard Rectifier

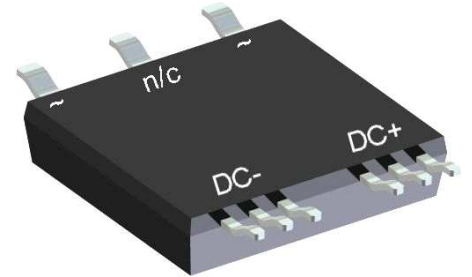
1~ Rectifier
$V_{RRM} = 1200\text{ V}$
$I_{DAV} = 124\text{ A}$
$I_{FSM} = 400\text{ A}$

1~ Rectifier Bridge


Part number

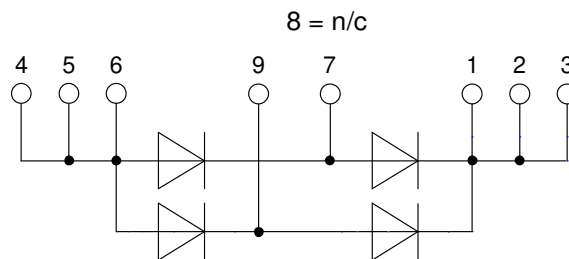
DLA100B1200LB

Marking on Product: DLA100B1200LB



Backside: isolated

 E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode Bridge for main rectification

Package: SMPD

- Isolation Voltage: 3000 V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

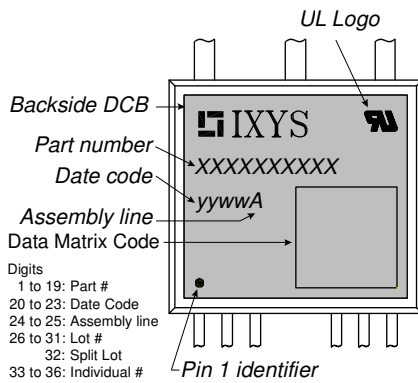
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Rectifier				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
I_R	reverse current	$V_R = 1200 V$	$T_{VJ} = 25^{\circ}C$		10	μA	
		$V_R = 1200 V$	$T_{VJ} = 150^{\circ}C$		0.1	mA	
V_F	forward voltage drop	$I_F = 50 A$	$T_{VJ} = 25^{\circ}C$		1.23	V	
					1.45	V	
		$I_F = 100 A$	$T_{VJ} = 150^{\circ}C$		1.15	V	
					1.44	V	
I_{DAV}	bridge output current	$T_C = 135^{\circ}C$	$T_{VJ} = 175^{\circ}C$		124	A	
		180° sine					
V_{FO}	threshold voltage	} for power loss calculation only	$T_{VJ} = 175^{\circ}C$		0.75	V	
r_F	slope resistance				4.2	m Ω	
R_{thJC}	thermal resistance junction to case				1	K/W	
R_{thCH}	thermal resistance case to heatsink			0.40		K/W	
P_{tot}	total power dissipation		$T_C = 25^{\circ}C$		150	W	
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$		400	A	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		430	A	
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}C$		340	A	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		365	A	
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$		800	A ² s	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		770	A ² s	
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}C$		580	A ² s	
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{ sine}$	$V_R = 0 V$		555	A ² s	
C_J	junction capacitance	$V_R = 400 V; f = 1 \text{ MHz}$	$T_{VJ} = 25^{\circ}C$		13	pF	



Package SMPD		Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			100	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				8.5		g
F_C	mounting force with clip		40		130	N
$d_{Spp/ App}$	creepage distance on surface / striking distance through air	terminal to terminal	1.6			mm
$d_{Spb/ Apb}$		terminal to backside	4.0			mm
V_{ISOL}	isolation voltage	t = 1 second	3000			V
		t = 1 minute	2500			V



Part description

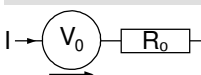
- D = Diode
- L = Low Voltage Standard Rectifier
- A = (up to 1200V)
- 100 = Current Rating [A]
- B = 1~ Rectifier Bridge
- 1200 = Reverse Voltage [V]
- LB = SMPD-B

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DLA100B1200LB-TUB	DLA100B1200LB	Tube	20	517180
Alternative	DLA100B1200LB-TRR	DLA100B1200LB	Tape & Reel	200	517187

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 175\text{ °C}$



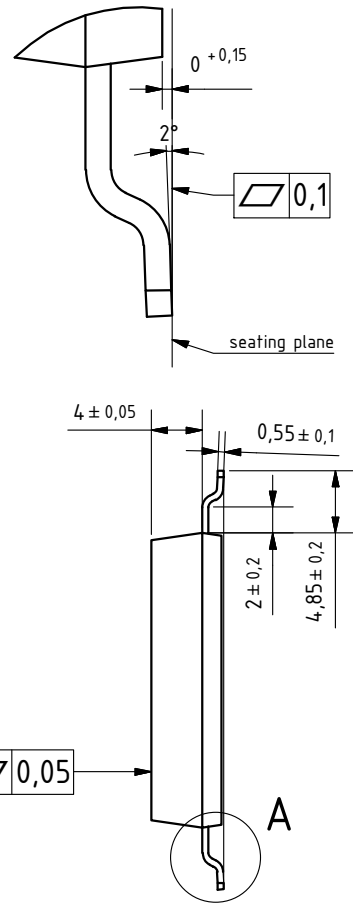
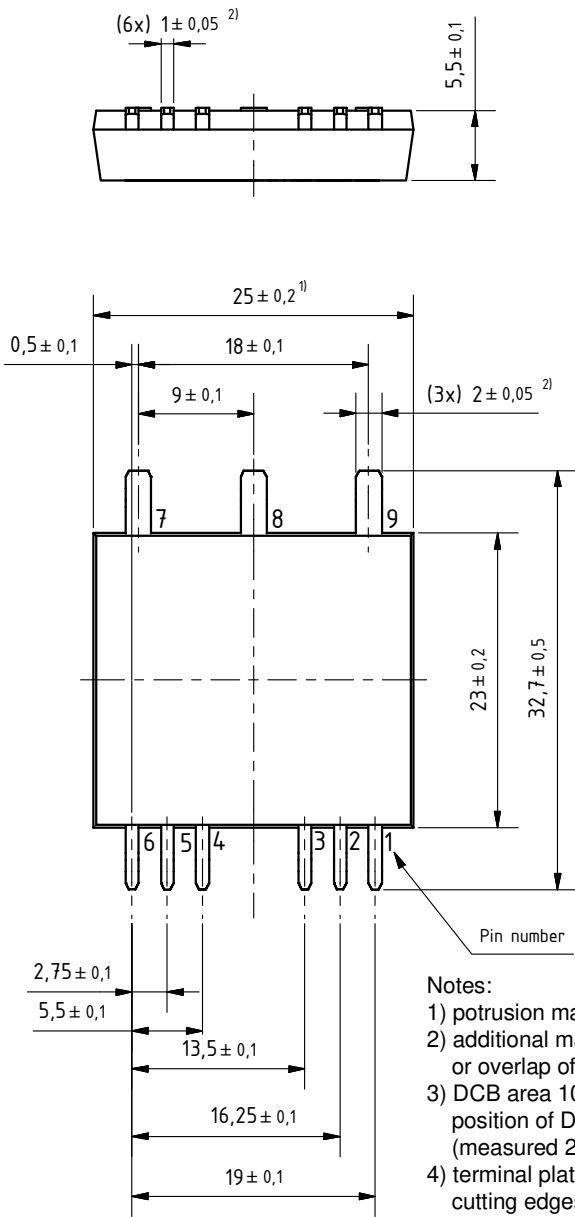
Rectifier

$V_{0\ max}$	threshold voltage	0.51	V
$R_{0\ max}$	slope resistance *	1.3	mΩ

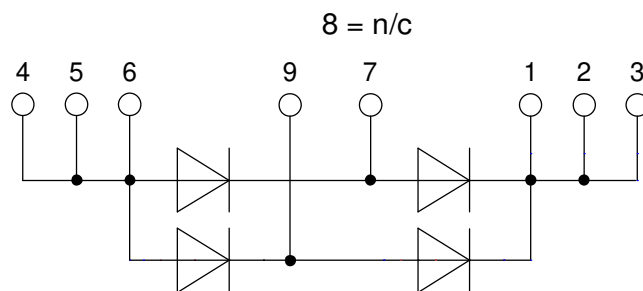


Outlines SMPD

A (8 : 1)



- Notes:
- 1) potrusion may add 0.2 mm max. on each side
 - 2) additional max. 0.05 mm per side by punching misalignment or overlap of dam bar or bending compression
 - 3) DCB area 10 to 50 μm convex; position of DCB area in relation to plastic rim: $\pm 25 \mu\text{m}$ (measured 2 mm from Cu rim)
 - 4) terminal plating: 0.2 - 1 μm Ni + 10 - 25 μm Sn (gal v.) cutting edges may be partially free of plating



Rectifier

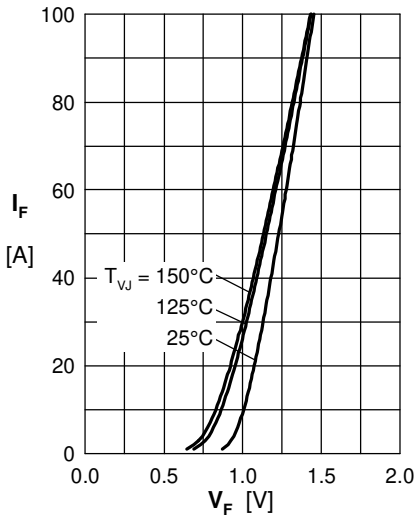


Fig. 1 Forward current versus voltage drop per diode

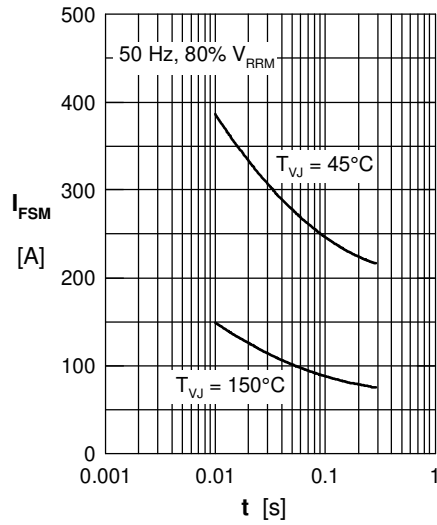


Fig. 2 Surge overload current

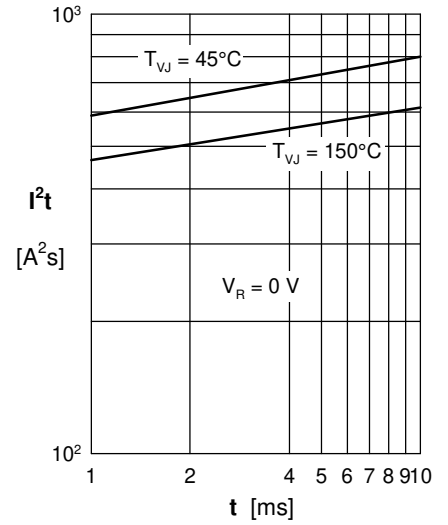


Fig. 3 I^2t versus time per diode

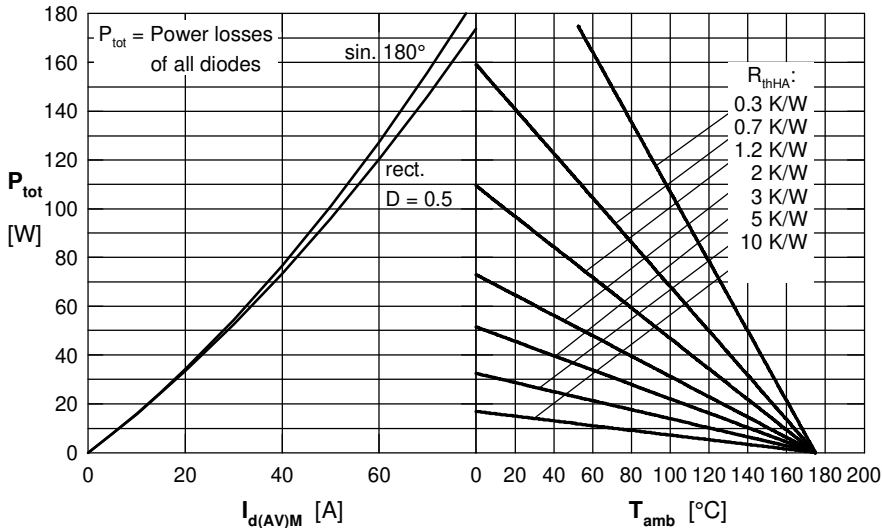


Fig. 4 Power dissipation vs. bridge output current and ambient temperature

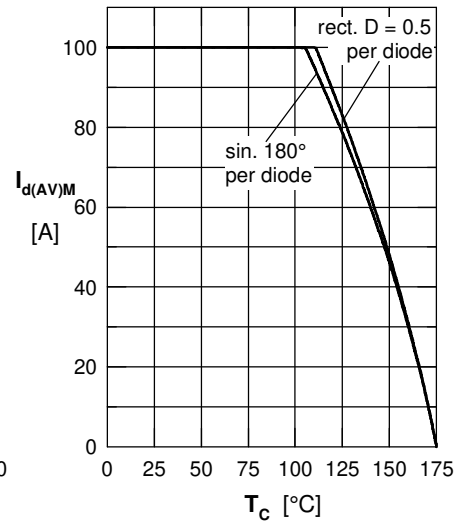


Fig. 5 Max. bridge output current vs. case temperature

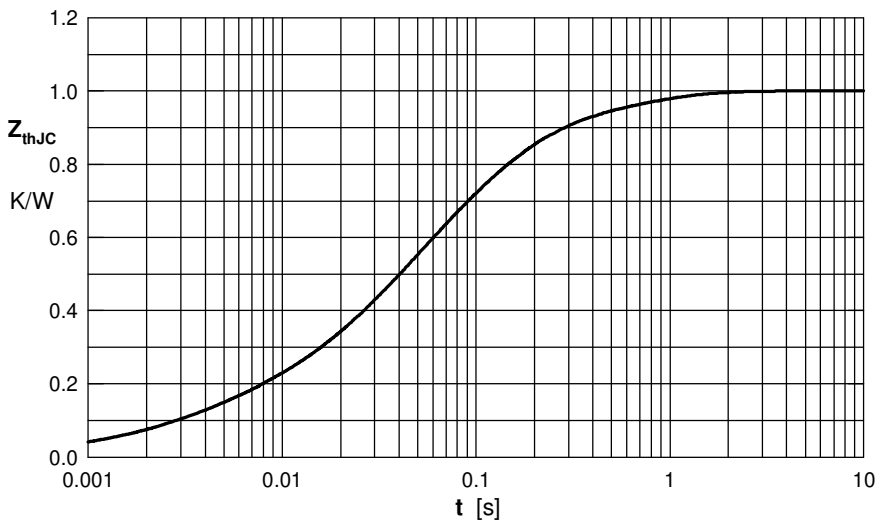


Fig. 6 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.09	0.003
2	0.116	0.062
3	0.386	0.1
4	0.128	0.55